

2016.12.19

“SEMICON JAPAN 2017” had finished successfully. Thank you for visiting the booth of A.L.M.T. Corp.

A.L.M.T.Corp. will exhibit range of innovative diamond wheels, tools, dies for wafer processing at "SEMICON Japan 2017" to be held at Tokyo Big Sight in Tokyo, Japan from Wednesday 13 to Friday 15, December 2017.

Taking this opportunity, please visit our booth and share the cutting-edge technology information for your further development.

A.L.M.T.Corp. supports your dynamic production.

"SEMICON Japan 2017"

- Date : December 13 (Wed) – December 15 (Fri), 2017
- Venue : Tokyo Big Sight, Tokyo , Japan
- Booth No. : Hall East2 2237

- Major Exhibits
【Diamond tools】

(Grinding tools)

“Nanomate Premium” for SiC, Si, GaN and LT wafer :
Highly precise grinding (Low-load grinding)

(Cutting and Grooving Tools)

Circular saw (Small saw) to cut non-ferrous metals accurately and efficiently
High Rigid Body Cutting Wheels
High precision thin cemented carbide cutter

(Wire Drawing Diamond Dies)

Diamond Drawing Dies for bonding wire

【High-performance heatspreader materials】

Newly released Heatspreader Materials MgSiC and CuMo for IGBT

Please refer further detailed information with regards to the exhibition to
→<http://www.semiconjapan.org/en/>